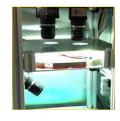
## Offline camera-inspection modusAOI MCS10

Optical inspection with the new stand-alone camera system allows for inexpensive and flexible testing of several production processes. Inspection with the high definition system camera (10-42 megapixels) is controlled and analysed with a Microsoft based computer and the proprietary modus AOI-software.



## **Technical information**

Camera Unit C10-42	Resolution 10 - 42 megapixels Aspect ratio 3:2, resolution is depend on image siz RGB-color filter on CCD-line sensor, Color intensity 24 bit, 3840 x 2748 pixels or 7716 x 5364 pixels
Light source	LED cluster white and red
Lens	1:1,4 - 25,5 mm, other lenses optionally
Operating range with standard lens	Operation range 75 mm x 88 mm [2.95 in. x 3.46 in.] Minimum distance of camera 150 mm [5.9 in.]
Test Speed	Image acquisition including analysis: 2 seconds typical
Software	Professional test software modusAOI 9.10 or higher Clearly arranged program with indication of error position and display of error- and comparing picture Intuitive programming with graphical interface Powerful and flexible test algorithms Integrated statistics, saving of data (traceability) Integration into function tests via open interfaces
System PC	Intel I5 3.3 GHz, 8 GB RAM, DVD-RW, network adaptor 2 x 1 Gb/s, I/O card, 1 TB hard disc, Windows XP 64, keyboard, mouse, block keyboard, 19" TFT-screen
Dimensions and Weight	Camera unit 39 mm x 39 mm [1.54 in. x 1.54 in.] height 40 mm [1.57 in.], weight ca. 300 g (0.66 lbs)
Connected values and Setting conditions	230 V / 50 Hz P1 or 110 V / 60 Hz power consumption PC: 300 W power consumption monitor: 120 W
Optionen	Activation of several camera units (combining to a check plan) Automatically start of test by sensor or switch Integrated capture of barcodes and data matrix codes Customer specific function test (external software)







## **Characteristics**

- Single system for the inspection of objects within an offline application. (One Piece Flow)
- Combination of various inspection tasks such as SMD-THT-UV, bond inspection as well as laser solder inspection.
- Typical tests include confirmation of the mechanical assembly, presence, placement and orientation of plugs, stickers, fixings, reading of barcode and data-matrix codes.

38 39